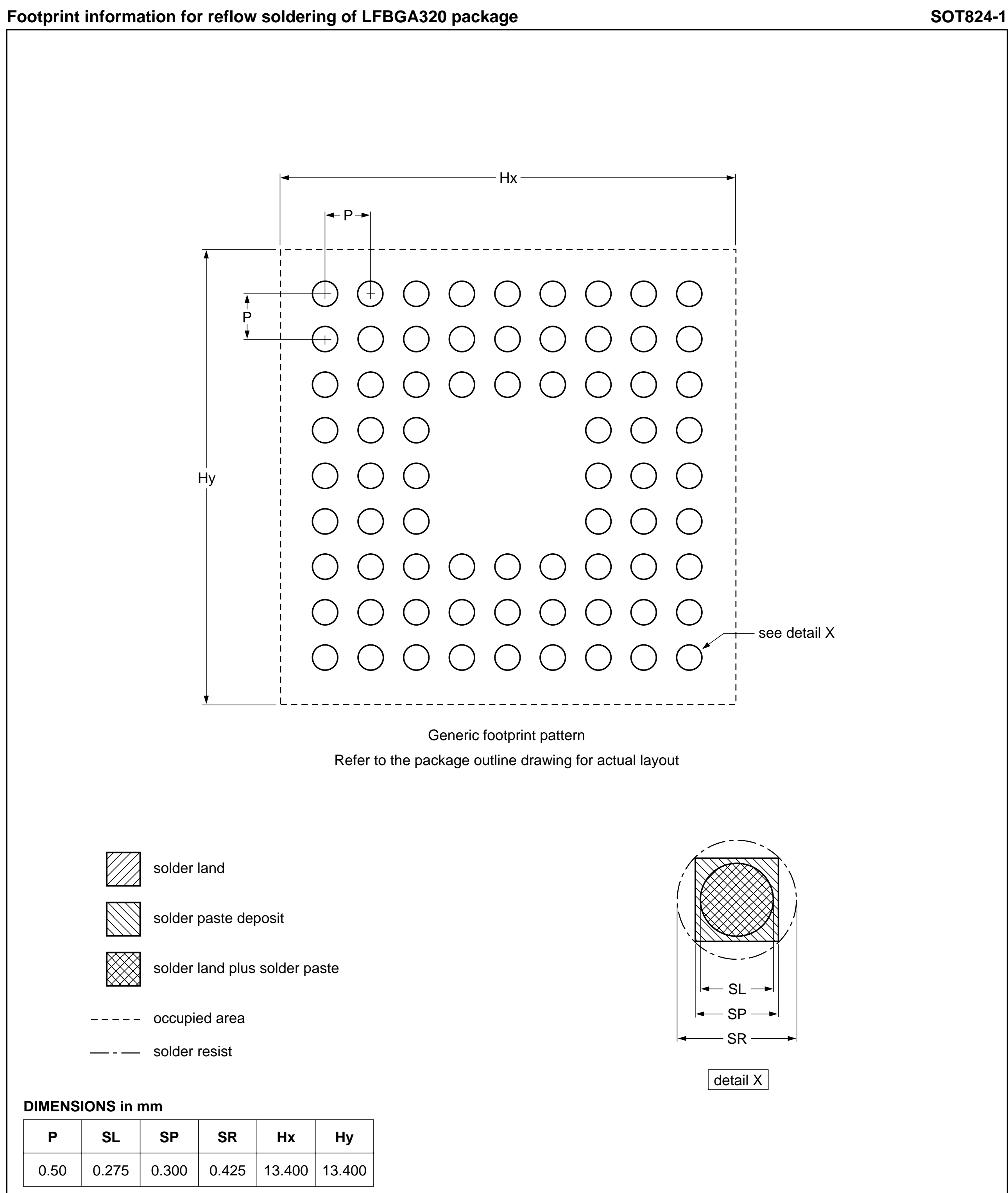
Footprint information for reflow soldering of LFBGA320 package

SOT824-1



Generic footprint pattern

Refer to the package outline drawing for actual layout

DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	13.400	13.400

SOT824-1_fr

© Koninklijke Philips Electronics N.V. 2006. All rights reserved.